



S/America  
3-8-02

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

1  
2 EXAMINER: N. PAREKH )  
3 APPLICANT: PETER ELENIUS, ET AL. ) Art Unit 2811  
4 SERIAL NO.: 09/575,298 )  
5 FILED: May 19, 2000 )  
6 FOR: "SOLDER BAR FOR HIGH POWER )  
7 FLIP CHIPS" )

8  
9 I hereby certify that this correspondence is being deposited with the United  
10 States Postal Service as first class mail in an envelope addressed to:  
11 Commissioner for Patents, Washington, D.C. 20231 on: January 28, 2002

12 Marvin A. Glazer

13 Name of Registered Rep.

14 Marvin A. Glazer  
15 Signature

16 Jan. 28, 2002  
17 Date

18 AMENDMENT

19 Honorable Commissioner for Patents  
20 Washington, D.C. 20231

21 Sir:

22 IN THE CLAIMS:

23 Please amend claim 16 as follows:

24 16. (Amended) A reflowable solder bar formed upon an upper surface of a first  
25 substrate, the first substrate having a first electrical contact, said reflowable solder bar being  
26 adapted to join the first electrical contact to a second electrical contact on a second substrate,  
27 said reflowable solder bar comprising in combination:

28 a. a first generally circular solder pad formed upon the upper surface of the first  
substrate, the first generally circular solder pad having a center, and having a first  
predetermined diameter D;

b. a second generally circular solder pad formed upon the upper surface of the first  
substrate, the second generally circular solder pad having a center, and having said first

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